2SB 1413

Silicon PNP Epitaxial Planar Type

AF Power Amplifier Complementary Pair with 2SD2133

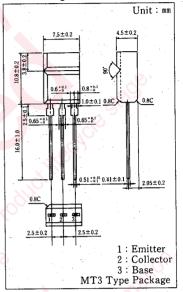
■ Feature

• Automatic mounting by radial taping is possible.

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Collector-base voltage	V _{CBO}	-45	v
Collector-emitter voltage	V _{CEO}	-,35	V
Emitter-base voltage	V _{EBO}	-5	V
Peak collector current	I _{CP}	-1.5	A
Collector current	Ic	-1	Α
Collector power dissipation	P _C	1.5	W
Junction temperature	T _i	150	°C
Storage temperature	$T_{\rm stg}$	-55~+150	° (%)
	·		

■ Package Dimensions

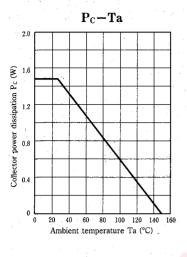


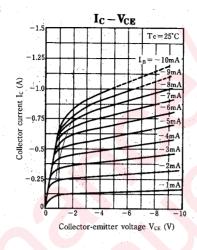
■ Electrical Characteristics (Tc=25°C)

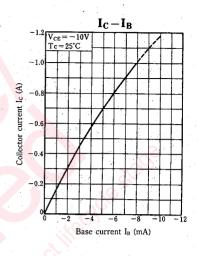
Item	Symbol	Condition	min.	typ.	max.	Unit	
	I _{CBO}	$V_{CB} = -20V, I_E = 0$. e5	-0.1	.,,	
Collector cutoff current	I_{CEO}	$V_{CE} = -20V, I_B = 0$	94.	0	-100	-100 μA	
Emitter cutoff current	I _{EBO}	$V_{EB} = -5V, I_C = 0$			-10	μ A	
Collector-base voltage	V _{CBO}	$I_{\rm C} = -10\mu{\rm A}, I_{\rm E} = 0$	45	SO.		V	
Collector-emitter voltage	V _{CEO}	$I_C = -2mA$, $I_B = 0$	-35	0		V	
DC current gain	h _{FE1} *	$V_{CE} = -10V, I_{C} = -500 \text{mA}$	85		340		
	h _{FE2}	$V_{CE} = -5V, I_{C} = -1A$	50				
Collector-emitter saturation voltage	V _{CE} (sat)	$I_{C} = -500 \text{mA}, I_{B} = -50 \text{mA}$			-0.5	V	
Transition frequency f_T $V_{CB} = -1$		$V_{CB} = -10V$, $I_E = 50mA$, $f = 200MHz$		200		MHz	
Collector output capacitance C_{ob} $V_{CB} = -10V$, I		$V_{CB} = -10V$, $I_E = 0$, $f = 1MHz$		20	30	pF	

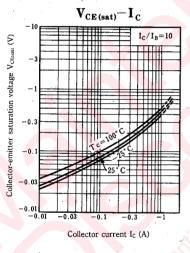
*hFE1 Classifications

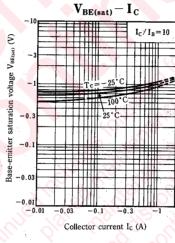
Class	Q	R	S
h _{FE1}	85~170	120~240	170~340

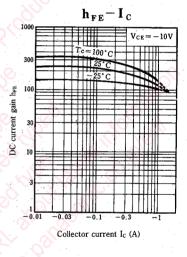


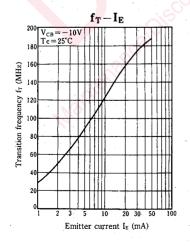


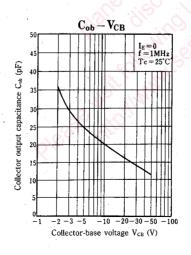


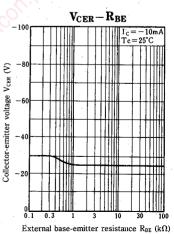


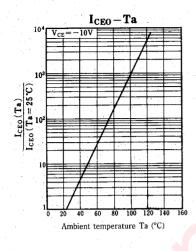


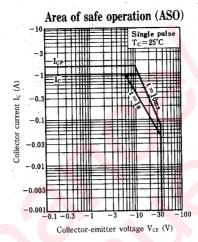


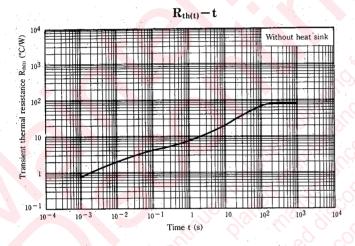












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